

**Amendments to the Claims:**

The following claims will replace all prior versions of the claims in this application (in the unlikely event that no claims follow herein, the previously pending claims will remain):

- 1-10. (Canceled)
11. (Currently amended) An integrated circuit package comprising:
  - a first leadframe;
  - a second leadframe laminated to a portion of a ~~side~~ surface of said first leadframe thereby providing a multi-layer laminated leadframe;
  - a semiconductor die mounted to another portion of said ~~side~~ surface of said first leadframe; and
  - a plurality of contact balls mounted on said semiconductor die.
12. (Previously presented) An integrated circuit package comprising:
  - a first leadframe;
  - a second leadframe laminated to a portion of said first leadframe thereby providing a multi-layer laminated leadframe;
  - a semiconductor die having opposing first and second surfaces, the first surface of said semiconductor die being mounted to another portion of said first leadframe; and
  - a third leadframe laminated to at least a portion of said second surface of said semiconductor die.
13. (Previously presented) The integrated circuit package according to claim 11, wherein said first leadframe comprises a copper strip having silver plating on one surface and said second leadframe is soldered to an opposing second surface thereof.
14. (Previously presented) The integrated circuit package according to claim 11, wherein said second leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

15. (Original) The integrated circuit package according to claim 12, wherein said third leadframe comprises a copper strip having a solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

16. (Previously presented) The integrated circuit package according to claim 11 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.